1 Mean, standard deviation, entropy maps of the patterns

1.1 Definitions

- $IQ_M = \frac{1}{W \cdot H} \sum_{i=1}^{W} \sum_{j=1}^{H} I_{ij}$
  - ◇ W: Pattern width
  - ◇ H: Pattern height
  - ◇ I_{ij}: Intensity (0-255) of the pixel at row i and column j
- $IQ_\sigma = \sqrt{\frac{\sum_{i=1}^{W} \sum_{j=1}^{H} I_{ij} - \bar{I}}{W \cdot H - 1}}$
  - ◇ W: Pattern width
  - ◇ H: Pattern height
  - ◇ I_{ij}: Intensity (0-255) of the pixel at row i and column j
  - ◇ $\bar{I}$: Average intensity (i.e. IQ_M)
- $IQ_E = -\sum_{i=0}^{2} 55 P_i \ln P_i$
  - ◇ P_i: Probability of gray level i

1.2 Advantages

- Less noise than IQ [2]
- Show micro-twins and scratches [2]
- Show small topography changes [2]
- Show strain levels [2]
- Don't rely on the detection of Kikuchi bands [2]
- Entropy maps have similar results than IQ [2]
- More related to surface topography [4]
- IQ_M very similar to FSD images (but with inverted contrast [4]
- IQ_M is mostly a measured of the overall backscatter yield (good for phase differentiation) [4]

1.3 Disadvantages

- Deteriorate with time due to contamination [2]
- Affected by gain and contrast settings of the EBSD detector unit as well as the SEM [4]
- Normalization is done using the hypothesis that the sum of all pixels in one row is constant [2]

1.4 Representation

- Black is assigned to all values less than 3σ and white to all values greater than 3σ [4]

2 Image Quality

2.1 Definitions

- $IQ_{HT} = \frac{1}{N} \sum_{i=1}^{N} H(\rho_i, \theta_i)$
  - ◇ N: number of peaks detected by the Hough transform (user defined value)
  - ◇ $H(\rho_i, \theta_i)$: Height of the ith peak
  - ◇ IQ_{HT} will be dependent on the user's selection. Because the peaks are found in decreasing order of intensity, if fewer peaks are allowed, IQ_{HT} will be large.
- Normalization
  - ◇ $IQ_{\text{normalized}} = \frac{IQ_{\text{initial}}}{IQ_{\text{standard}}}$
    - ∗ IQ_{standard}: Average IQ value of a standard sample (no deformation)
  - ◇ $IQ_{\text{normalized}} = \frac{IQ_{\text{initial}} - IQ_{\text{min}}}{IQ_{\text{max}} - IQ_{\text{min}}}$
    - ∗ IQ_{min}: Minimum IQ value of a set
    - ∗ IQ_{max}: Maximum IQ value of a set

2.2 Factors

- Elastic strain [4]
  - ◇ "Bend" strain → More diffuse bands
  - ◇ "Stretch" strain → Wider bands
- Plastic strain [4]
  - ◇ Superposition of individual patterns → More diffuse patterns
- Composition [4]
  - ◇ Heavier atoms have higher atomic scattering factors (brighter patterns)
- Surface topology [4]

2.3 Advantages

- Similar to confidence index [2]
- Metric describing the quality of a diffraction pattern [4]
- Doesn't show charge buildup (horizontal artifacts) like the mean, standard dev. and entropy does [4]
- Show boundaries (grain and phase) [4]
- Best map to differentiate between phases, grain boundaries and strain [4]
- Best contrast between strain and unstrained regions [4]
- IQ differences arising from orientation differences are generally mush smaller than those due to phase, grain boundaries or strain [4]
- Normalization minimized the effect of image processing on the IQ values [5]

2.4 Disadvantages

- Rely on the detection of Kikuchi bands (influence by false peaks) [2]
- Affected by various operator-defined parameters used in the calculation of the Hough transform [4]
- No distinction between high and low angles grain boundaries [4]
- IQ values are not corrected for the grain boundary contribution [5]
  - ◇ Pixels around grain boundary should be removed from the IQ value

3 Multi-peaks Model

3.1 Definitions

- $N = \sum_{i=1}^{k} n_i$
- $IQ \approx \sum_{i=1}^{k} ND(n_i, \mu_i, \sigma_i)$
  - ◇ N: Number of the total scan points in a file
  - ◇ k: Number of normal distributions in the simulation
  - ◇ ND: Normal distribution
- Conditions
  1. $Min(k)$
  2. $\left\| IQ - \sum_{i=1}^{k} ND(n_i, \mu_i, \sigma_i) \right\| \leq \epsilon$
     - ◇ ϵ: Minimum acceptable error

3.2 Advantages

- Study of multi-component microstructures [5]

4 Fourier Transform

4.1 Definitions

- Contrast [3]
  - ⋄ Root mean square intensity of averaged band profiles
  - ⋄ One dimension profiles were taken normal to the band at 1 pixel intervals along the length and superimposed, resulting in a projection of the average profile of the band
  - ⋄ Bands nearly parallel to the selected band do contribute peaks in the profile, which are broadened by the misalignment with the projection direction
  - ⋄ These features can be removed from the projected intensity profile by using a suitable window or weighting function
  - ⋄ Hanning function was used: $H(x) = \frac{1}{2}\cos(2\pi x/X)$
    - ∗ x: Sample number
    - ∗ X: Total number of samples in the profile
  - ⋄ The central peak is emphasizes, while the outer regions regions of the profile are continuously attenuated
- Sharpness/Diffuseness [3]
  - ⋄ In a good quality pattern, the edges involve rapid changes in intensity (high frequency are present)
  - ⋄ In a degraded pattern, the gray level changes at the edges occur more graduaylly (high frequency attenuated)
  - ⋄ The attenuation of high frequency components of Fourier transform of the enhanced images and of the averaged band profiles
  - ⋄ Two methods
    1. Spectral first peak area (SFPA)
       - ∗ Calculate the area under the first peak in the power spectrum obtained from the projected average intensity profile
       - ∗ Apply the Hanning function to the profile prior to transformation in order to emphasize the central Kikuchi band and to reduce leakage encountered in the use of discrete Fourier analysis.
       - ∗ Take the fraction between the area under the first peak and the total area of the spectrum (independent of pattern quality)
    2. Power spectra first moment (PSFM)
       - ∗ Use to generate a single value quantifying the quality of Kikuchi band profiles
       - ∗ As the method is highly sensitive to the position at which any one single profile is taken, the use of 2D Fourier analysis reduces this dependence on positions
       - ∗ Integration of the 2D spectrum around circular paths at each radii allows average coefficients at each frequency to be determined
       - ∗ Hanning function is used
       - ∗ Take the fraction between the first moment by the area under the spectrum (independent of pattern contrast)

4.2 Factors

- Strain
  - ⋄ Steady decrease in the high frequency Fourier components as strain increases
  - ⋄ Diffuseness of EBSP patterns is observed to increase with plastic strain

4.3 Advantages

- Cold work reduces both contrast and sharpness [3]
- Tilt effect contrast, but not sharpness [3]

4.4 Disadvantages

- Measurements are dependent on the contamination [3]
- Sampling of several grains is essential to build a calibration curve [3]

5 Band Contrast

5.1 Definitions

- Jump in contrast between the edge of the band and the adjacent background [1]

5.2 Disadvantages

- Not sufficient to reliably capture the deformation gradients [1]

6 Misorientation Mapping

6.1 Definitions

- Method [1]
  1. Establish grains in microstructure
  2. Determine the reference pixel for every individual grain
     - ◇ Calculate the mis-orientation for all nine-pixels clusters within a given grain, disregarding boundary pixels
     - ◇ Choose the cluster with least mis-orientation as reference (minimum distortion)
  3. Calculate and map the mis-orientation
     - ◇ For a given grain, calculate the mis-orientation between each pixel and the reference pixel
     - ◇ Map this mis-orientation for each pixel using a color table

6.2 Advantages

- Small mis-orientations represent small amount of intra-grain mis-orientation / lattice rotation and therefore large deformations [1]
- Scratches are visible [1]
- Show extent of deformation zone [1]
- Sensitive to deformation on a grain-by-grain basis [1]

6.3 Disadvantages

- Lack of connection to more quantitative measures of deformation such as strain, strain gradient or dislocation density [1]
- The choice of the reference mis-orientation can substantially affect the resulting map [1]
- Not accurate enough to measure elastic strain [1]

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